



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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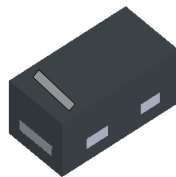


## Features

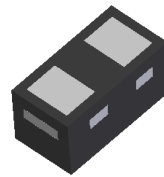
- Ultra-Small Leadless Surface Mount Package (0.6 x 0.3mm)
- Ultra-Low Profile Package (0.3mm)
- Ideally Suited for Automated Assembly Processes
- Low Leakage Current, Suitable for Battery-Powered Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **Halogen and Antimony Free "Green" Device (Notes 2 & 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

- Case: X3-DFN0603-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish – Matte Tin over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.2 mg (Approximate)



Top View



Bottom View

## Ordering Information (Note 4)

Part Number	Case	Packaging
GDZ8V2BLP3-7	X3-DFN0603-2	10,000/Tape & Reel

- Notes:
1. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free
  2. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  3. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
  4. For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



xx = Product Marking Code  
(See Electrical Characteristics Table)  
Line Denotes Cathode Side

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) $T_A = 25^\circ\text{C}$	$P_D$	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5) $T_A = 25^\circ\text{C}$	$R_{\theta JA}$	500	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

## Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Type Number	Marking Code	Zener Voltage Range (Note 6)				Maximum Reverse Current (Note 6)	
		$V_Z @ I_{ZT}$			$I_{ZT}$ mA	$I_R$ $\mu\text{A}$	@ $V_R$ V
		Nom (V)	Min (V)	Max (V)			
GDZ8V2BLP3	KI, KR	8.2	7.995	8.405	5	0.5	5.0

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at <http://www.diodes.com>.
  - Short duration pulse test used to minimize self-heating effect.

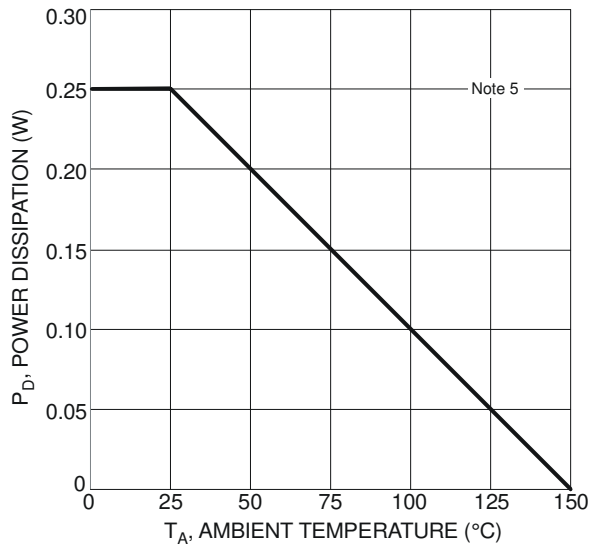


Fig. 1 Power Derating Curve

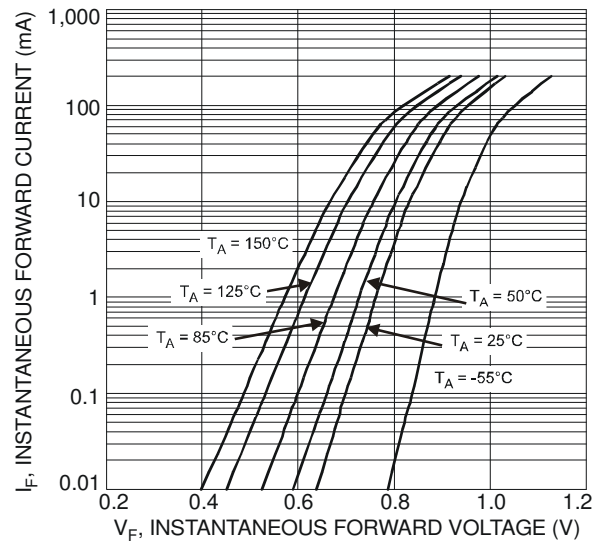


Fig. 2 Typical Forward Characteristics

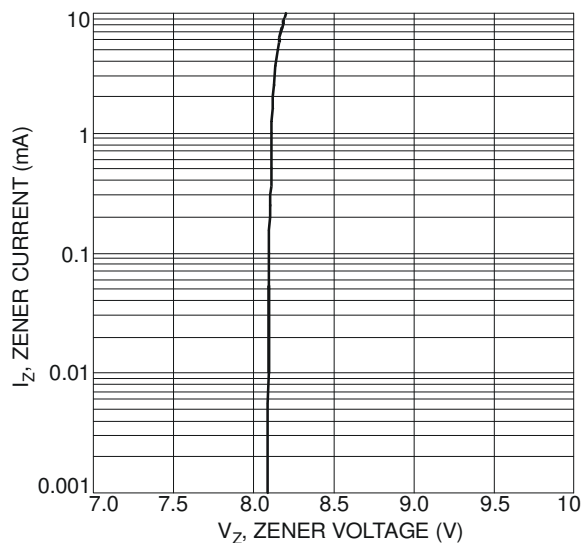


Fig. 3 Typical Zener Breakdown Characteristics

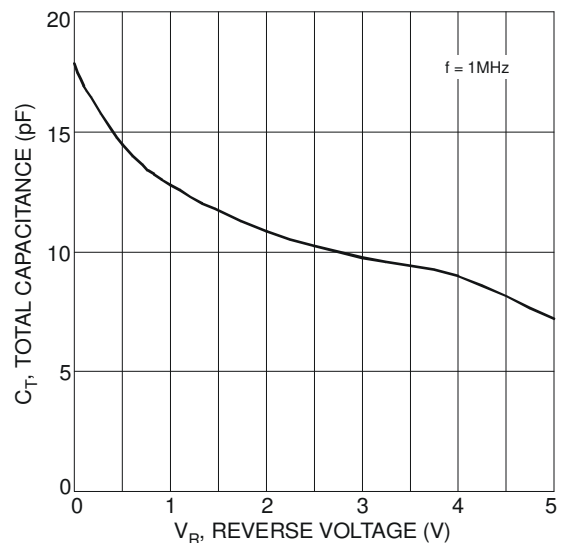
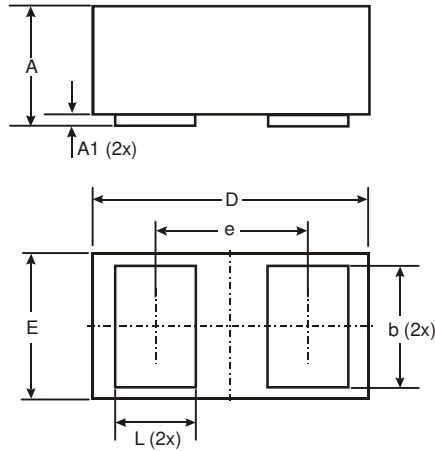


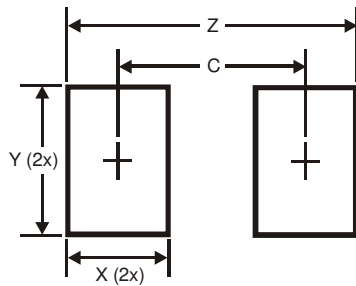
Fig. 4 Typical Total Capacitance

**Package Outline Dimensions**



X3-DFN0603-2			
Dim	Min	Max	Typ
A	0.27	0.35	0.30
A1	0.00	0.03	0.02
b	0.19	0.29	0.24
D	0.595	0.645	0.62
E	0.295	0.345	0.32
e	-	-	0.355
L	0.14	0.24	0.19
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**



Dimensions	Value (in mm)
C	0.355
X	0.230
Y	0.300
Z	0.610

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